

## Press Release

Contact: Casey Krawiec FOR IMMEDIATE RELEASE

Phone: 1 (858)674-4676 9 A.M. EDT, September 18,2012

## QUIK-PAK EXPANDS NEW Open-molded PLASTIC PACKAGE (Ompp)PRODUCT FAMILY WITH 8-LEAD SOIC

San Diego, CA, September 18, 2012, - Quik-Pak, a division of Delphon Industries and leader in Microelectronic Packaging and Assembly, announces its 8-Lead SOIC (Small Outline Integrated Circuit), the newest addition to the Open-molded Plastic Package (OmPP)™ product line. This 0.150″ narrow body package is built to JEDEC standard MS-012 and is RoHS compliant. It is Ni/Au plated which is excellent for wire bonding. Quik-Pak's 8-Lead SOIC has a standard 0.050″ lead pitch and a superior sealing surface for air cavity applications.

Quik-Pak's OmPP product family includes pre-molded QFN (Quad Flat No-Lead) and SOIC package configurations that are designed to provide a high quality, quick, and cost-effective solution for your IC packaging and assembly needs. The company's Open-molded packages offer flexibility and are ideal for prototype or

production volume applications. Quik-Pak's OmPP packages are production quality and are available for rapid delivery to meet customer's timelines and specifications.

## .About Quik-Pak:

The company specializes in microelectronic packaging and advanced assembly services. A limitless array of open-cavity and open molded packages are available with no minimum quantity. Packaging can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, remolding and marking/branding. Custom assembly services are also offered for flip chip, ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced costs for new devices, while providing excellent flexibility, quality and customer service.

## For further information:

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